

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM739780

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
CMC MATERIALS, INC.		07/06/2022	Corporation: DELAWARE
INTERNATIONAL TEST SOLUTIONS, LLC		07/06/2022	Limited Liability Company: DELAWARE
QED TECHNOLOGIES INTERNATIONAL, INC.		07/06/2022	Corporation: DELAWARE
RECEIVING PARTY DATA			
Name:	Morgan Stanley Senior Funding, Inc., as Collateral Agent		
Street Address:	1300 Thames Street, 4th Floor, Thames Street Wharf		
City:	Baltimore		
State/Country:	MARYLAND		
Postal Code:	21231		
Entity Type:	Corporation: DELAWARE		
PROPERTY NUMBERS Total: 60			
Property Type	Number	Word Mark	
Registration Number:	5520231	ACTIV-8	
Registration Number:	5788180	AUSCILLATER	
Registration Number:	3725048	CCW	
Registration Number:	5514443	CHAMELEON SEAL	
Registration Number:	1851237	CLEANROOM	
Serial Number:	88806340		
Registration Number:	6667318	CMC MATERIALS	
Registration Number:	6667339	CMC MATERIALS	
Registration Number:	2363181	EPIC	
Serial Number:	90581923	EPIC POWER	
Serial Number:	90581990	EPIC POWER	
Registration Number:	5944473	EQUA-LUBE EIGHTY	
Registration Number:	4479239	ETCH CLEAN	
Registration Number:	5514442	FLOW WOLF	
Registration Number:	1705722	GIGABIT	
Registration Number:	5807265	GRIZZLY SEAL	

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Property Type	Number	Word Mark
Registration Number:	2994247	HIPR
Registration Number:	2517587	ICUE
Registration Number:	4613239	IDIEL
Registration Number:	2651534	INTERNATIONAL TEST SOLUTIONS
Registration Number:	2632288	LUSTRA
Registration Number:	5354755	MEDEA
Registration Number:	2827173	MRF
Registration Number:	3306579	NANO-STRIP
Registration Number:	3949164	NANO-STRIP
Registration Number:	3702810	NEXPLANAR
Registration Number:	2599807	PROBE CLEAN
Registration Number:	2642325	PROBE FORM
Registration Number:	3251735	PROBE LAP
Registration Number:	2610970	PROBE POLISH
Registration Number:	3660513	PROBE POLISH
Registration Number:	5947138	PROBE REFRESH
Registration Number:	3660514	PROBE SCRUB
Registration Number:	2599808	PROBE SCRUB
Registration Number:	5947139	PROBE VERTICAL
Registration Number:	4303897	QED OPTICS
Registration Number:	2777617	QED TECHNOLOGIES
Registration Number:	4270737	Q-FLEX
Registration Number:	3725049	SCD
Registration Number:	5969362	SEALVALVE
Registration Number:	6010732	SEALVALVE
Registration Number:	2142260	SEALWELD
Registration Number:	6085978	SEALWELD
Registration Number:	1704025	SEMI-SPERSE
Registration Number:	1917115	SEMI-SPERSE
Registration Number:	3103184	SILECT
Registration Number:	4517513	STAGE CLEAN
Registration Number:	5938368	SUPERGUN
Registration Number:	3820328	TCC
Registration Number:	1870262	TERABIT
Registration Number:	5638495	TOTAL-LUBE #911
Registration Number:	3623364	TRANSELE
Registration Number:	2971771	TURBOFLO
Registration Number:	1907795	ULTRA-ETCH

Property Type	Number	Word Mark
Registration Number:	5633402	UNI-SEAL
Registration Number:	5498636	VALVE CLEANER PLUS
Registration Number:	5938369	VALVEPRO
Registration Number:	4053560	VIPER
Registration Number:	3456932	WIN
Registration Number:	2243649	X-PAND

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 8004945225
Email: ipteam@cogencyglobal.com
Correspondent Name: JAY DASILVA
Address Line 1: 1025 CONNECTICUT AVE., NW, STE. 712
Address Line 2: COGENCY GLOBAL INC.
Address Line 4: WASHINGTON, D.C. 20036

ATTORNEY DOCKET NUMBER:	1735218 TM C
NAME OF SUBMITTER:	Sharif Hamidi
SIGNATURE:	/Sharif Hamidi/
DATE SIGNED:	07/08/2022

Total Attachments: 26

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PATENT AND TRADEMARK SECURITY AGREEMENT dated as of July 6, 2022 (this "Agreement"), among CMC MATERIALS, INC., a Delaware corporation, INTERNATIONAL TEST SOLUTIONS, LLC, a Delaware limited liability company, and QED TECHNOLOGIES INTERNATIONAL, INC. (each, a "Grantor" and, together, the "Grantors") and MORGAN STANLEY SENIOR FUNDING, INC., as Collateral Agent.

Reference is made to (a) the Credit and Guaranty Agreement dated as of November 6, 2018, as amended and restated as of July 6, 2022 (as it may be further amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), among Entegris Inc., a Delaware corporation (the "Company"), certain Subsidiaries of the Company party thereto, the Lenders party thereto and Morgan Stanley Senior Funding, Inc., as Administrative Agent and Collateral Agent, and (b) the Pledge and Security Agreement referred to therein. The Lenders have agreed to extend credit to the Company subject to the terms and conditions set forth in the Credit Agreement. The Grantors party hereto are Affiliates of the Company, will derive substantial benefits from the extension of credit to the Company pursuant to the Credit Agreement and are willing to execute and deliver this Agreement in order to induce the Lenders to extend such credit or as consideration for credit previously extended continuing to be outstanding. Accordingly, the parties hereto agree as follows:

SECTION 1. Terms. Each capitalized term used but not otherwise defined herein shall have the meaning specified in the Credit Agreement or the Collateral Agreement, as applicable. The rules of construction specified in Section 1.3 of the Credit Agreement also apply to this Agreement, mutatis mutandis.

SECTION 2. Grant of Security Interest. As security for the payment and performance in full of the Obligations, each Grantor pursuant to the Collateral Agreement did, and hereby does, grant to the Collateral Agent, its successors and assigns, for the benefit of the Secured Parties, a security interest in all of such Grantor's right, title and interest in, to and under any and all of the following assets now owned or at any time hereafter acquired by such Grantor or in, to or under which such Grantor now has or at any time hereafter may acquire any right, title or interest (collectively, the "Patent and Trademark Collateral"):

(a) (i) all letters patent of the United States of America or the equivalent thereof in any other country, all registrations and recordings thereof and all applications for letters patent of the United States of America or the equivalent thereof in any other country or any political subdivision thereof, including registrations, recordings and pending applications in the United States Patent and Trademark Office or any similar offices in any other country or any political subdivision thereof, including, in the case of any Grantor, any of the foregoing set forth under its name on Schedule I hereto, and (ii) all reissues, continuations, divisionals, continuations-in-part, reexaminations, supplemental examinations, inter partes reviews, renewals, adjustments or extensions thereof, and the inventions disclosed or claimed therein, including the right to make, have made, use, sell, offer to sell, import or export the inventions disclosed or claimed therein; and

(b) (i) all trademarks, service marks, trade names, corporate names, company names, business names, fictitious business names, trade styles, trade dress, logos, domain

names, global top level domain names, other source or business identifiers, designs and general intangibles of like nature, all registrations and recordings thereof, and all registration and recording applications filed in connection therewith, including registrations and registration applications in the United States Patent and Trademark Office or any similar office in any State of the United States of America or any other country or any political subdivision thereof, all extensions or renewals thereof, and all common law rights related thereto, including, in the case of any Grantor, any of the foregoing set forth under its name on Schedule II hereto, (ii) all goodwill associated therewith or symbolized thereby and (iii) all other assets, rights and interests that uniquely reflect or embody such goodwill.

SECTION 3. Collateral Agreement. The security interests granted to the Collateral Agent herein are granted in furtherance of, and not in limitation of, the security interests granted to the Collateral Agent pursuant to the Collateral Agreement. Each Grantor hereby acknowledges and affirms that the rights and remedies of the Collateral Agent with respect to the Patent and Trademark Collateral are more fully set forth in the Collateral Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Collateral Agreement, the terms of the Collateral Agreement shall govern.

SECTION 4. Counterparts. This Agreement may be executed in counterparts (and by different parties hereto on different counterparts), each of which shall constitute an original but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart of a signature page of this Agreement by fax, emailed pdf or any other electronic means that reproduces an image of the actual executed signature page shall be effective as delivery of a manually executed counterpart of this Agreement.

SECTION 5. Incorporation by Reference. The provisions of Sections 6.02, 6.04, 6.05, 6.08, 6.09 and 6.10 of the Collateral Agreement are hereby incorporated by reference herein as if set forth in full force herein, mutatis mutandis.

[Signature Page Follows]

IN WITNESS WHEREOF, the parties hereto have duly executed this Agreement as of the day and year first above written.

CMC MATERIALS, INC.,
as Grantor

By: DocuSigned by:
Greg Graves _____
Name: 23BA975C0B4A4E9... Graves
Title: Executive Vice President and
Chief Financial Officer

INTERNATIONAL TEST SOLUTIONS, LLC,
as Grantor

By: *H. Carol Bernstein*
Name: H. Carol Bernstein
Title: Vice President, Secretary and General Counsel

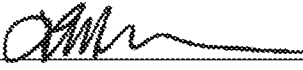
**QED TECHNOLOGIES INTERNATIONAL,
INC.,** as Grantor

By: *H. Carol Bernstein*
Name: H. Carol Bernstein
Title: Vice President, Secretary and General Counsel

[Signature Page to Patent and Trademark Security Agreement]

TRADEMARK
REEL: 007773 FRAME: 0671

**MORGAN STANLEY SENIOR
FUNDING, INC., as Collateral Agent**

By: _____

Name: Lisa Hanson

Title: Executive Director

SCHEDULE I

Patents and Patent Applications

Registered Owner	Title	Application Number	Patent Number	Filing Date
QED Technologies International, Inc.	DELIVERY SYSTEM FOR MAGNETORHEOLOGICAL FLUID	09/862,245	6,955,589	5/22/2001
CMC Materials, Inc.	DRAG REDUCING AGENT SLURRIES HAVING ALFOLALCOHOLS AND PROCESSES FOR FORMING DRAG REDUCING AGENT SLURRIES HAVING ALFOLALCOHOLS	09/877,341	7,012,046	6/8/2001
CMC Materials, Inc.	ANIONIC ABRASIVE PARTICLES TREATED WITH POSITIVELY CHARGED POLYELECTROLYTES FOR CMP	10/073,844	6,776,810	2/11/2002
CMC Materials, Inc.	CMP COMPOSITIONS FOR LOW-K DIELECTRIC MATERIALS	10/165,100	6,974,777	6/7/2002
CMC Materials, Inc.	BULK POLYMERIZATION REACTOR METHODS	10/170,785	7,582,708	6/12/2002
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING CONDUCTING POLYMER	10/199,704	6,811,474	7/19/2002
QED Technologies International, Inc.	UNIFORM THIN FILMS PRODUCED BY MAGNETORHEOLOGICAL FINISHING	10/213,631	6,746,310	8/6/2002
CMC Materials, Inc.	SLURRY FOR MECHANICAL POLISHING (CMP) OF METALS AND USE THEREOF	10/231,047	6,812,193	8/30/2002
CMC Materials, Inc.	USE OF NON-IONIC SURFACTANTS TO REDUCE Ta AND OXIDE REMOVAL RATE	10/269,864	6,936,543	10/11/2002
CMC Materials, Inc.	MICROPOROUS POLISHING PADS	10/281,782	6,913,517	10/28/2002
CMC Materials, Inc.	TRANSPARENT MICROPOROUS MATERIALS FOR CMP	10/282,489	7,435,165	10/28/2002
CMC Materials, Inc.	POLISHING COMPOSITIONS AND USE THEREOF	10/295,836	6,641,632	11/18/2002
QED Technologies International, Inc.	METHOD FOR SELF-CALIBRATED SUB-APERTURE STITCHING FOR SURFACE FIGURE MEASUREMENT	10/303,236	6,956,657	11/25/2002
CMC Materials, Inc.	CMP PAD WITH COMPOSITE TRANSPARENT WINDOW	10/361,520	6,960,120	2/10/2003
CMC Materials, Inc.	MIXED-ABRASIVE POLISHING COMPOSITION AND METHOD FOR USING THE SAME	10/364,243	6,896,591	2/11/2003
CMC Materials, Inc.	COATED METAL OXIDE PARTICLES FOR CMP	10/419,580	7,044,836	4/21/2003
CMC Materials, Inc.	MULTI-LAYER POLISHING PAD MATERIAL FOR CMP	10/463,680	6,884,156	6/17/2003

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	ULTRASONIC WELDING METHOD FOR THE MANUFACTURE OF A POLISHING PAD COMPRISING AN OPTICALLY TRANSMISSIVE REGION	10/463,721	6,997,777	6/17/2003
CMC Materials, Inc.	POLISHING PAD WITH ORIENTED PORE STRUCTURE	10/463,730	6,998,166	6/17/2003
CMC Materials, Inc.	CMP OF NOBLE METALS	10/610,407	7,160,807	6/30/2003
CMC Materials, Inc.	CHEMICAL MECHANICAL POLISHING COMPOSITION AND METHOD FOR USING THE SAME	10/660,379	7,485,241	9/11/2003
CMC Materials, Inc.	POLISHING PAD WITH RECESSED WINDOW	10/666,797	7,195,539	9/19/2003
QED Technologies International, Inc.	METHOD FOR CALIBRATING THE GEOMETRY OF A MULTI-AXIS METROLOGY SYSTEM	10/743,840	7,173,691	12/22/2003
CMC Materials, Inc.	CHEMICAL-MECHANICAL POLISHING OF METALS IN AN OXIDIZED FORM	10/753,138	7,288,021	1/7/2004
CMC Materials, Inc.	POLISHING SYSTEM COMPRISING A HIGHLY BRANCHED POLYMER	10/755,154	7,255,810	1/9/2004
CMC Materials, Inc.	METHOD OF POLISHING A SILICON-CONTAINING DIELECTRIC	10/543,848	7,442,645	2/2/2004
CMC Materials, Inc.	MICROPOROUS POLISHING PADS	10/792,183	6,896,593	3/3/2004
CMC Materials, Inc.	MICROPOROUS POLISHING PADS	10/792,344	6,899,598	3/3/2004
CMC Materials, Inc.	MICROPOROUS POLISHING PADS	10/792,348	6,935,931	3/3/2004
CMC Materials, Inc.	LOW SURFACE ENERGY CMP PAD	10/807,079	7,059,936	3/23/2004
CMC Materials, Inc.	CUSTOMIZED POLISH PADS FOR CHEMICAL MECHANICAL PLANARIZATION	10/810,070	7,425,172	3/25/2004
QED Technologies International, Inc.	METHOD AND APPARATUS FOR MEASURING AND CONTROLLING SOLIDS COMPOSITION OF A MAGNETORHEOLOGICAL FLUID	10/845,804	6,893,322	5/14/2004
CMC Materials, Inc.	METHOD OF POLISHING A TUNGSTEN-CONTAINING SUBSTRATE	10/869,397	7,247,567	6/16/2004
CMC Materials, Inc.	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS	10/897,192	7,377,840	7/21/2004
CMC Materials, Inc.	POLISHING COMPOSITION FOR NOBLE METALS	10/901,420	7,161,247	7/28/2004
CMC Materials, Inc.	POLISHING PAD WITH MICROPOROUS REGIONS	10/931,908	8,075,372	9/1/2004
CMC Materials, Inc.	CHEMICAL MECHANICAL POLISHING COMPOSITION AND METHOD FOR USING THE SAME	10/568,727	7,754,098	9/10/2004

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	METAL ION-CONTAINING CMP COMPOSITION AND METHOD FOR USING THE SAME	10/974,460	8,038,752	10/27/2004
CMC Materials, Inc.	CMP COMPOSITION COMPRISING SURFACTANT	10/975,585	7,524,347	10/28/2004
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS	10/982,486	7,504,044	11/5/2004
QED Technologies International, Inc.	METHOD AND APPARATUS FOR FORMING A DYNAMIC MAGNETIC SEAL USING MAGNETORHEOLOGICAL FLUID	11/012,645	7,156,724	12/15/2004
CMC Materials, Inc.	POLYMERIC INHIBITORS FOR ENHANCED PLANARIZATION	11/093,806	7,311,856	3/30/2005
CMC Materials, Inc.	MULTI-LAYER POLISHING PAD MATERIAL FOR CMP	11/113,498	7,435,161	4/25/2005
CMC Materials, Inc.	TRANSPARENT MICROPOROUS MATERIALS FOR CMP	11/158,694	7,267,607	6/22/2005
CMC Materials, Inc.	USE OF CMP FOR ALUMINUM MIRROR AND SOLAR CELL FABRICATION	11/173,518	8,062,096	6/30/2005
CMC Materials, Inc.	COMPOSITION AND METHOD FOR PLANARIZING SURFACES	11/241,137	7,955,519	9/30/2005
CMC Materials, Inc.	CUSTOMIZED POLISH PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF	11/251,547	7,704,125	10/14/2005
CMC Materials, Inc.	CMP OF COPPER/RUTHENIUM SUBSTRATES	11/259,645	7,265,055	10/26/2005
CMC Materials, Inc.	METHOD FOR MANUFACTURING MICROPOROUS CMP MATERIALS HAVING CONTROLLED PORE SIZE	11/265,607	7,311,862	11/2/2005
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS	11/294,853	7,531,105	12/6/2005
QED Technologies International, Inc.	METHOD FOR ACCURATE HIGH-RESOLUTION MEASUREMENTS OF ASPHERIC SURFACES	11/398,193	7,433,057	4/5/2006
CMC Materials, Inc.	BULK POLYMERIZATION REACTOR METHODS	11/406,110	7,534,403	4/18/2006
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING POLYETHER AMINE	11/412,369	7,585,340	4/27/2006
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR POLISHING SILICON NITRIDE MATERIALS	11/448,205	8,759,216	6/7/2006
CMC Materials, Inc.	TUNABLE SELECTIVITY SLURRIES IN CMP APPLICATIONS	11/478,023	7,294,576	6/29/2006
CMC Materials, Inc.	BULK POLYMERIZATION REACTORS	11/507,271	8,105,547	8/21/2006

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	ONIUM-CONTAINING CMP COMPOSITIONS AND METHODS OF USE THEREOF	11/517,909	9,129,907	9/8/2006
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR CMP OF LOW-K DIELECTRIC MATERIALS	11/595,536	7,456,107	11/9/2006
CMC Materials, Inc.	COMPOSITIONS FOR POLISHING ALUMINUM/COPPER AND TITANIUM IN DAMASCENE STRUCTURES	11/634,576	9,343,330	12/6/2006
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR CMP OF PHASE CHANGE ALLOYS COMPOSITIONS AND METHODS FOR CMP OF PHASE CHANGE ALLOYS	11/699,129	7,897,061	1/29/2007
CMC Materials, Inc.	METHOD OF POLISHING A TUNGSTEN-CONTAINING SUBSTRATE	11/670,137	7,582,127	2/1/2007
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR CMP OF SEMICONDUCTOR MATERIALS	11/673,399	7,803,203	2/9/2007
CMC Materials, Inc.	CMP SYSTEM UTILIZING HALOGEN ADDUCT	11/673,518	7,776,230	2/9/2007
QED Technologies International, Inc.	METHOD AND APPARATUS FOR MEASUREMENT OF MAGNETIC PERMEABILITY OF A MATERIAL	11/681,258	7,557,566	3/2/2007
CMC Materials, Inc.	CMP METHOD FOR METAL-CONTAINING SUBSTRATES	12/309,212	9,074,118 B2	7/6/2007
CMC Materials, Inc.	COPPER-PASSIVATING CMP COMPOSITIONS AND METHODS	11/986,921	7,955,520	11/27/2007
CMC Materials, Inc.	CUSTOMIZED POLISH PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF	11/998,319	8,864,859	11/28/2007
CMC Materials, Inc.	CUSTOMIZED POLISH PADS FOR CHEMICAL MECHANICAL PLANARIZATION	11/998,196	7,704,122	11/28/2007
CMC Materials, Inc.	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS	11/998,212	8,287,793	11/28/2007
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING NICKEL-PHOSPHOROUS-COATED ALUMINUM HARD DISKS	11/970,978	7,922,926	1/8/2008
QED Technologies International, Inc.	METHOD AND APPARATUS FOR MEASUREMENT OF MAGNETIC PERMEABILITY OF A MATERIAL	12/449,655	7,888,929	2/27/2008
CMC Materials, Inc.	SILICON CARBIDE POLISHING METHOD UTILIZING WATER-SOLUBLE OXIDIZERS	12/043,010	7,998,866	3/5/2008

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	COMPOSITIONS FOR POLISHING ALUMINUM/COPPER AND TITANIUM IN DAMASCENE STRUCTURES	12/052,970	8,425,797	3/21/2008
CMC Materials, Inc.	STABLE, HIGH RATE SILICON SLURRY	12/126,739	8,017,524	5/23/2008
CMC Materials, Inc.	METHOD OF POLISHING NICKEL-PHOSPHOROUS	12/170,954	8,247,326	7/10/2008
CMC Materials, Inc.	METHODS AND COMPOSITIONS FOR POLISHING SILICON-CONTAINING SUBSTRATES	12/221,023	8,247,327	7/30/2008
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE	12/234,173	7,994,057	9/19/2008
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE	12/234,237	9,028,572	9/19/2008
CMC Materials, Inc.	METHOD OF POLISHING A SILICON-CONTAINING DIELECTRIC	12/239,249	8,486,169	9/26/2008
CMC Materials, Inc.	CUSTOMIZED POLISHING PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF	11/884,829	8,715,035	10/16/2008
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS	12/364,253	7,846,842	2/2/2009
CMC Materials, Inc.	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS	12/364,937	8,226,841	2/3/2009
CMC Materials, Inc.	GROOVED CMP PAD	12/381,709	9,180,570	3/16/2009
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD FOR HIGH SILICON NITRIDE TO SILICON OXIDE REMOVAL RATE RATIOS	12/384,266	8,138,091	4/2/2009
QED Technologies International, Inc.	STITCHING OF NEAR-NULLED SUBAPERTURE MEASUREMENTS	12/384,723	8,203,719	4/8/2009
CMC Materials, Inc.	POLISHING PAD CARRIER	29/337,774	D640057	5/29/2009
CMC Materials, Inc.	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS	12/455,631	9,330,703	6/4/2009
CMC Materials, Inc.	DRAG REDUCING COMPOSITIONS AND METHODS OF MANUFACTURE AND USE	12/996,055	8,669,304	6/9/2009
CMC Materials, Inc.	POLISHING SYSTEMS	12/456,546	8,383,003	6/18/2009
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING POLYETHER AMINE	12/462,067	8,741,009	7/29/2009
CMC Materials, Inc.	BARRIER SLURRY FOR LOW-K DIELECTRICS	12/584,343	8,252,687	9/3/2009

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING BULK SILICON	12/462,638	8,883,034	9/16/2009
CMC Materials, Inc.	BULK POLYMERIZATION REACTORS FOR PRODUCING DRAG REDUCER	12/589,749	8,110,150	10/28/2009
CMC Materials, Inc.	DRAG REDUCING AGENT AND METHOD OF USE	12/589,818	8,106,114	10/29/2009
CMC Materials, Inc.	METHOD TO SELECTIVELY POLISH SILICON CARBIDE FILMS	12/630,288	9,548,211	12/3/2009
International Test Solutions, LLC	APPARATUSES, DEVICE, AND METHODS FOR CLEANING TESTER INTERFACE CONTACT ELEMENTS AND SUPPORT HARDWARE	12/630,714	8,371,316	12/3/2009
CMC Materials, Inc.	CMP PAD WITH LOCAL AREA TRANSPARENCY	12/657,135	9,017,140	1/13/2010
QED Technologies International, Inc.	SYSTEM FOR MAGNETORHEOLOGICAL FINISHING OF A SUBSTRATE	13/254,640	8,944,883	3/2/2010
CMC Materials, Inc.	CMP POROUS PAD WITH PARTICLES IN A POLYMERIC MATRIX	12/761,016	9,951,054	4/15/2010
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING BULK SILICON	12/762,180	8,815,110	4/16/2010
CMC Materials, Inc.	OXIDATION-STABILIZED CMP COMPOSITIONS AND METHODS	12/764,268	8,497,209	4/21/2010
CMC Materials, Inc.	CUSTOMIZED POLISH PADS FOR CHEMICAL MECHANICAL PLANARIZATION	12/767,712	8,380,339	4/26/2010
CMC Materials, Inc.	CMP COMPOSITIONS AND METHODS FOR SUPPRESSING POLYSILICON REMOVAL RATES	13/379,911	8,691,695	6/18/2010
CMC Materials, Inc.	SOFT POLISHING PAD FOR POLISHING A SEMICONDUCTOR SUBSTRATE	12/832,908	9,156,124	7/8/2010
CMC Materials, Inc.	COMPOSITIONS FOR CMP OF SEMICONDUCTOR MATERIALS	12/854,470	8,529,680	8/11/2010
CMC Materials, Inc.	SILICON POLISHING COMPOSITIONS WITH HIGH RATE AND LOW DEFECTIVITY	12/807,324	8,273,142	9/2/2010
CMC Materials, Inc.	METHOD OF FABRICATING A POLISHING PAD WITH AN END-POINT DETECTION REGION FOR EDDY CURRENT END-POINT DETECTION	12/895,529	8,439,994	9/30/2010
CMC Materials, Inc.	POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION	12/895,465	8,628,384	9/30/2010
CMC Materials, Inc.	HOMOGENEOUS POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION	12/895,479	8,657,653	9/30/2010

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CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING POLYSILICON	12/971,714	8,697,576	12/17/2010
QED Technologies International, Inc.	SYSTEM FOR MAGNETORHEOLOGICAL FINISHING OF SUBSTRATES	12/977,180	8,613,640	12/23/2010
CMC Materials, Inc.	POLISHING PAD WITH MULTI-MODAL DISTRIBUTION OF PORE DIAMETERS	12/979,123	8,702,479	12/27/2010
CMC Materials, Inc.	METAL-PASSIVATING CMP COMPOSITIONS AND METHODS	13/004,113	8,435,421	1/11/2011
CMC Materials, Inc.	POLISHING PAD WITH CONCENTRIC OR APPROXIMATELY CONCENTRIC POLYGON GROOVE PATTERN	13/014,630	9,211,628	1/26/2011
QED Technologies International, Inc.	METHOD AND APPARATUS FOR MEASUREMENT AND CONTROL OF MAGNETIC PARTICLE CONCENTRATION IN A MAGNETORHEOLOGICAL FLUID	13/085,688	8,896,293	4/13/2011
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR SELECTIVE POLISHING OF SILICON NITRIDE MATERIALS	13/087,857	8,808,573	4/15/2011
CMC Materials, Inc.	POLISHING PAD WITH ALIGNMENT FEATURE	13/101,826	8,968,058	5/5/2011
CMC Materials, Inc.	POLISHING PAD WITH ALIGNMENT APERTURE	13/184,395	8,920,219	7/15/2011
CMC Materials, Inc.	DRAG REDUCING COMPOSITIONS AND METHODS OF MANUFACTURE AND USE	13/817,564	9,416,331	8/23/2011
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING ALUMINUM SEMICONDUCTOR SUBSTRATES	13/237,881	8,623,766	9/20/2011
International Test Solutions, LLC	APPARATUSES, DEVICE, AND METHODS FOR CLEANING TESTER INTERFACE CONTACT ELEMENTS AND SUPPORT HARDWARE	13/290,015	8,801,869	11/4/2011
International Test Solutions, LLC	APPARATUSES, DEVICE, AND METHODS FOR CLEANING TESTER INTERFACE CONTACT ELEMENTS AND SUPPORT HARDWARE	13/290,017	8,790,466	11/4/2011
CMC Materials, Inc.	POLISHING PAD WITH GROOVED FOUNDATION LAYER AND POLISHING SURFACE LAYER	13/306,849	9,067,298	11/29/2011
CMC Materials, Inc.	POLISHING PAD WITH FOUNDATION LAYER AND POLISHING SURFACE LAYER	13/306,845	9,067,297	11/29/2011
CMC Materials, Inc.	SILICON POLISHING COMPOSITIONS WITH IMPROVED PSD PERFORMANCE	13/351,339	9,425,037	1/17/2012
CMC Materials, Inc.	POLISHING PAD WITH LIGHT-STABLE LIGHT-TRANSMITTING	13/444,620	9,156,125	4/11/2012

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	REGION			
CMC Materials, Inc.	CMP COMPOSITION CONTAINING ZIRCONIA PARTICLES AND METHOD OF USE	13/477,535	8,778,212	5/22/2012
CMC Materials, Inc.	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS-COATED MEMORY DISKS	13/478,292	9,039,914	5/23/2012
CMC Materials, Inc.	POLISHING PAD WITH POLISHING SURFACE LAYER HAVING AN APERTURE OR OPENING ABOVE A TRANSPARENT FOUNDATION LAYER	13/488,149	9,597,769	6/4/2012
CMC Materials, Inc.	POLISHING COMPOSITION FOR NICKEL-PHOSPHOROUS MEMORY DISKS	13/546,128	8,557,137	7/11/2012
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR SELECTIVE POLISHING OF SILICON NITRIDE MATERIALS	13/546,552	9,633,863	7/11/2012
QED Technologies International, Inc.	MAGNETORHEOLOGICAL FLUID FOR ULTRASMooth POLISHING	13/551,786	9,157,010	7/18/2012
CMC Materials, Inc.	COMPOSITIONS FOR POLISHING SILICON-CONTAINING SUBSTRATES	13/554,829	8,597,540	7/20/2012
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING HYBRID ABRASIVE FOR NICKEL-PHOSPHOROUS COATED MEMORY DISKS	13/594,947	8,518,135	8/27/2012
CMC Materials, Inc.	POLYPYRROLIDONE POLISHING COMPOSITION AND METHOD	13/606,599	8,821,215	9/7/2012
CMC Materials, Inc.	METHODS FOR PRODUCING IN-SITU GROOVES IN CHEMICAL MECHANICAL PLANARIZATION (CMP) PADS, AND NOVEL CMP PAD DESIGNS	13/612,135	8,932,116	9/12/2012
International Test Solutions, LLC	WAFER MANUFACTURING CLEANING APPARATUS, PROCESS AND METHOD OF USE	13/725,827	10,002,776	12/21/2012
CMC Materials, Inc.	POLISHING PAD HAVING POLISHING SURFACE WITH CONTINUOUS PROTRUSIONS	13/747,139	9,649,742	1/22/2013
CMC Materials, Inc.	CHEMICAL-MECHANICAL POLISHING COMPOSITION CONTAINING ZIRCONIA AND METAL OXIDIZER	13/754,413	8,920,667	1/30/2013
CMC Materials, Inc.	POLISHING SYSTEMS	13/757,163	9,272,388	2/1/2013

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CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING GLASS	13/784,330	9,358,659	3/4/2013
CMC Materials, Inc.	DRAG REDUCING COMPOSITIONS AND METHODS OF MANUFACTURE AND USE	13/791,093	8,933,149	3/8/2013
CMC Materials, Inc.	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY	13/799,680	8,916,061	3/13/2013
CMC Materials, Inc.	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY	13/799,920	9,238,753	3/13/2013
CMC Materials, Inc.	POLISHING PAD HAVING POLISHING SURFACE WITH CONTINUOUS PROTRUSIONS HAVING TAPERED SIDEWALLS	13/829,990	10,160,092	3/14/2013
CMC Materials, Inc.	CMP COMPOSITIONS WITH LOW SOLIDS CONTENT AND METHODS RELATED THERETO	13/841,344	8,961,807	3/15/2013
CMC Materials, Inc.	METHOD FOR POLISHING ALUMINUM/COPPER AND TITANIUM IN DAMASCENE STRUCTURES	13/846,126	8,623,767	3/18/2013
CMC Materials, Inc.	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY	13/898,842	8,906,252	5/21/2013
CMC Materials, Inc.	COMPOSITIONS AND METHODS FOR CMP OF SILICON OXIDE, SILICON NITRIDE, AND POLYSILICON MATERIALS	13/947,449	9,303,187	7/22/2013
International Test Solutions, LLC	Working surface cleaning system and method	13/961,127	9,833,818	8/7/2013
International Test Solutions, LLC	WAFER MANUFACTURING CLEANING APPARATUS, PROCESS AND METHOD OF USE	13/971,619	9,595,456	8/20/2013
CMC Materials, Inc.	CHEMICAL-MECHANICAL PLANARIZATION OF POLYMER FILMS	14/035,037	9,434,859	9/24/2013
CMC Materials, Inc.	WET-PROCESS CERIA COMPOSITIONS FOR SELECTIVELY POLISHING SUBSTRATES, AND METHODS RELATED THERETO	14/050,722	9,279,067	10/10/2013
CMC Materials, Inc.	WET-PROCESS CERIA COMPOSITIONS FOR POLISHING SUBSTRATES, AND METHODS	14/050,977	9,281,210	10/10/2013

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	RELATED THERETO			
CMC Materials, Inc.	MIXED ABRASIVE POLISHING COMPOSITIONS	14/051,121	9,340,706	10/10/2013
CMC Materials, Inc.	POLISHING PAD WITH OFFSET CONCENTRIC GROOVING PATTERN AND METHOD FOR POLISHING A SUBSTRATE THEREWITH	14/440,209	9,687,956	11/5/2013
QED Technologies International, Inc.	INTEGRATED WAVEFRONT SENSOR AND PROFILOMETER	14/087,363	9,097,612 B2	11/22/2013
CMC Materials, Inc.	CMP COMPOSITIONS AND METHODS FOR POLISHING NICKEL-PHOSPHOROUS SURFACES	14/094,921	10,358,579	12/3/2013
CMC Materials, Inc.	POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION	14/099,655	9,028,302	12/6/2013
CMC Materials, Inc.	CMP COMPOSITIONS AND METHODS FOR SELECTIVE REMOVAL OF SILICON NITRIDE	14/100,339	9,850,402	12/9/2013
CMC Materials, Inc.	HOMOGENEOUS POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION	14/152,792	9,597,777	1/10/2014
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS	14/156,201	9,909,032	1/15/2014
CMC Materials, Inc.	POLISHING PAD WITH MULTI-MODAL DISTRIBUTION OF PORE DIAMETERS	14/183,894	9,555,518	2/19/2014
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN CMP	14/203,621	9,238,754	3/11/2014
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN CMP	14/203,647	9,303,188	3/11/2014
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN CMP	14/203,693	9,303,189	3/11/2014
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN BUFFING	14/222,086	9,309,442	3/21/2014
CMC Materials, Inc.	MIXED ABRASIVE TUNGSTEN CMP COMPOSITION	14/222,736	9,303,190	3/24/2014
CMC Materials, Inc.	MIXED ABRASIVE TUNGSTEN CMP COMPOSITION	14/222,716	9,127,187	3/24/2014
CMC Materials KK	SLURRY COMPOSITION AND METHOD OF SUBSTRATE POLISHING	14/784,527	9,528,031	4/25/2014
CMC Materials, Inc.	POLISHING COMPOSITION FOR EDGE ROLL-OFF IMPROVEMENT	14/269,622	9,401,104	5/5/2014
CMC Materials, Inc.	CMP COMPOSITIONS SELECTIVE FOR OXIDE OVER POLYSILICON AND NITRIDE WITH HIGH REMOVAL RATE AND LOW DEFECTIVITY	14/289,728	9,165,489	5/29/2014

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CMC Materials, Inc.	POLISHING PAD HAVING POROGENS WITH LIQUID FILLER	14/307,846	9,238,294	6/18/2014
International Test Solutions, LLC	APPARATUSES, DEVICE, AND METHODS FOR CLEANING TESTER INTERFACE CONTACT ELEMENTS AND SUPPORT HARDWARE	14/445,003	10,195,648	7/28/2014
CMC Materials, Inc.	POLISHING PAD WITH POROUS INTERFACE AND SOLID CORE, AND RELATED APPARATUS AND METHODS	14/459,452	9,463,551	8/14/2014
CMC Materials, Inc.	DRAG REDUCING COMPOSITIONS AND METHODS OF MANUFACTURE AND USE	14/466,367	9,267,094	8/22/2014
CMC Materials, Inc.	CUSTOMIZED POLISHING PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF	14/489,177	9,278,424	9/17/2014
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING BULK SILICON	14/509,081	9,701,871	10/8/2014
CMC Materials, Inc.	CMP POLISHING PAD HAVING EDGE EXCLUSION REGION OF OFFSET CONCENTRIC GROOVE PATTERN	14/515,560	9,409,276	10/16/2014
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD FOR NICKEL-PHOSPHOROUS COATED MEMORY DISKS	14/515,723	9,534,147	10/16/2014
CMC Materials, Inc.	POLISHING PAD WITH HOMOGENEOUS BODY HAVING DISCRETE PROTRUSIONS THEREON	14/530,534	9,296,085	10/31/2014
CMC Materials, Inc.	POLISHING PAD WITH APERTURE	14/550,129	9,597,770	11/21/2014
CMC Materials, Inc.	CMP COMPOSITIONS EXHIBITING REDUCED DISHING IN STI WAFER POLISHING	14/568,311	9,422,455	12/12/2014
Lee Krywitsky and CMC Materials, Inc.	SAFETY CLOSURES AND PUMPING SYSTEMS	14/577,453	10,184,469	12/19/2014
CMC Materials, Inc.	POLISHING PAD WITH ALIGNMENT FEATURE	14/610,991	9,249,273	1/30/2015
CMC Materials, Inc.	LOW DENSITY POLISHING PAD	14/611,064	10,946,495	1/30/2015
CMC Materials, Inc.	CMP COMPOSITION FOR SILICON NITRIDE REMOVAL	14/612,736	9,803,109	2/3/2015
CMC Materials, Inc.	CMP METHOD FOR SUPPRESSION OF TITANIUM NITRIDE AND TITANIUM/TITANIUM NITRIDE REMOVAL	14/616,250	9,752,057	2/6/2015
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED EDGE ROLL-OFF	14/627,081	9,481,811	2/20/2015

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CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING CERIA ABRASIVE	14/639,564	9,505,952	3/5/2015
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING CATIONIC POLYMER ADDITIVE	14/639,598	9,758,697	3/5/2015
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE	14/657,594	9,617,450	3/13/2015
CMC Materials KK	SLURRY COMPOSITION AND METHOD FOR POLISHING SUBSTRATE	15/126,543	9,914,853	3/17/2015
CMC Materials, Inc.	MULTI-LAYER POLISHING PAD FOR CMP	14/700,580	9,818,618	4/30/2015
CMC Materials, Inc.	POLISHING PAD WITH GROOVED FOUNDATION LAYER AND POLISHING SURFACE LAYER	14/727,586	9,931,729	6/1/2015
CMC Materials, Inc.	POLISHING PAD WITH FOUNDATION LAYER AND POLISHING SURFACE LAYER	14/732,497	9,931,728	6/5/2015
CMC Materials, Inc.	COLLOIDAL SILICA CHEMICAL MECHANICAL POLISHING COMPOSITION	14/749,923	9,422,456	6/25/2015
CMC Materials, Inc.	COLLOIDAL SILICA CHEMICAL-MECHANICAL POLISHING COMPOSITION	14/749,948	9,499,721	6/25/2015
CMC Materials, Inc.	COLLOIDAL SILICA CHEMICAL-MECHANICAL POLISHING CONCENTRATE	14/750,107	9,422,457	6/25/2015
CMC Materials, Inc.	TUNGSTEN CHEMICAL-MECHANICAL POLISHING COMPOSITION	14/750,204	9,567,491	6/25/2015
CMC Materials, Inc.	COPPER BARRIER CHEMICAL-MECHANICAL POLISHING COMPOSITION	14/750,271	9,556,363	6/25/2015
CMC Materials, Inc.	METHODS FOR FABRICATING A CHEMICAL-MECHANICAL POLISHING COMPOSITION	14/750,050	9,803,106	6/25/2015
CMC Materials, Inc.	CLEANING COMPOSITION FOLLOWING CMP AND METHODS RELATED THERETO	15/327,326	10,100,272	7/17/2015
CMC Materials, Inc.	SELECTIVE NITRIDE SLURRIES WITH IMPROVED STABILITY AND IMPROVED POLISHING CHARACTERISTICS	14/849,066	9,597,768	9/9/2015
CMC Materials, Inc.	GROOVED CMP PADS	14/874,179	9,375,823	10/2/2015
CMC Materials, Inc.	NICKEL PHOSPHOROUS CMP COMPOSITIONS AND METHODS	14/881,837	9,469,787	10/13/2015
CMC Materials, Inc.	COBALT INHIBITOR COMBINATION FOR IMPROVED DISHING	14/918,756	9,528,030	10/21/2015

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CMC Materials, Inc.	CORROSION INHIBITORS AND RELATED COMPOSITIONS AND METHODS	14/919,404	10,124,464	10/21/2015
CMC Materials, Inc.	COBALT POLISHING ACCELERATORS	14/919,449	9,688,885	10/21/2015
CMC Materials, Inc.	COBALT DISHING CONTROL AGENTS	14/919,490	9,834,704	10/21/2015
CMC Materials, Inc.	SLURRY FOR CHEMICAL MECHANICAL POLISHING OF COBALT	14/919,526	9,944,828	10/21/2015
CMC Materials, Inc.	TUNGSTEN-PROCESSING SLURRY WITH CATIONIC SURFACTANT AND CYCLODEXTRIN	14/924,997	9,771,496	10/28/2015
CMC Materials, Inc.	TUNGSTEN-PROCESSING SLURRY WITH CATIONIC SURFACTANT	14/925,054	9,631,122	10/28/2015
CMC Materials, Inc.	POLISHING PAD WITH FOUNDATION LAYER AND WINDOW ATTACHED THERETO	14/931,737	9,868,185	11/3/2015
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN CMP	14/965,168	9,566,686	12/10/2015
CMC Materials, Inc.	TUNGSTEN PROCESSING SLURRY WITH CATALYST	14/988,891	10,066,126	1/6/2016
CMC Materials, Inc.	CLEANING COMPOSITION AND METHOD FOR CLEANING SEMICONDUCTOR WAFERS AFTER CMP	14/993,837	9,828,574	1/12/2016
CMC Materials, Inc.	CUSTOMIZED POLISHING PADS FOR CMP AND METHODS OF FABRICATION AND USE THEREOF	15/042,777	10,220,487	2/12/2016
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING CERIA PARTICLES AND METHOD OF USE	15/056,198	10,414,947	2/29/2016
CMC Materials, Inc.	CMP COMPOSITION AND METHOD FOR POLISHING RIGID DISKS	15/091,275	10,315,285	4/5/2016
CMC Materials, Inc.	METHODS AND COMPOSITIONS FOR PROCESSING DIELECTRIC SUBSTRATE	15/207,973	10,029,345	7/12/2016
CMC Materials, Inc.	POLYURETHANE CMP PADS HAVING A HIGH MODULUS RATIO	15/273,855	10,562,149	9/23/2016
CMC Materials, Inc.	POLISHING COMPOSITION CONTAINING CERIA ABRASIVE	15/338,724	9,828,528	10/31/2016
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE	15/346,835	10,508,219	11/9/2016
CMC Materials, Inc.	CMP PROCESSING COMPOSITION COMPRISING ALKYLAMINE AND CYCLODEXTRIN	15/394,090	9,796,882	12/29/2016
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING SILICON CARBIDE	15/398,933	10,294,399	1/5/2017

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CMC Materials, Inc.	POLISHING COMPOSITION COMPRISING CATIONIC POLYMER ADDITIVE	15/414,786	10,301,508	1/25/2017
International Test Solutions, LLC	WAFER MANUFACTURING CLEANING APPARATUS, PROCESS AND METHOD OF USE	15/419,840	10,109,504	1/30/2017
CMC Materials, Inc.	METHOD OF POLISHING GROUP III-V MATERIALS	15/433,068	10,418,248	2/15/2017
CMC Materials, Inc.	POLISHING PAD HAVING POLISHING SURFACE WITH CONTINUOUS PROTRUSIONS	15/479,779	10,293,459	4/5/2017
International Test Solutions, LLC	SEMICONDUCTOR WIRE BONDING MACHINE CLEANING DEVICE AND METHOD	15/495,873	9,825,000	4/24/2017
CMC Materials, Inc.	COBALT POLISHING ACCELERATORS	15/603,634	9,850,403	5/24/2017
CMC Materials, Inc.	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS FOR PROCESSING A NICKEL SUBSTRATE SURFACE	15/615,591	10,792,785	6/6/2017
CMC Materials, Inc.	POLISHING COMPOSITION COMPRISING AN AMINE-CONTAINING SURFACTANT	15/629,487	10,344,186	6/21/2017
CMC Materials, Inc.	ALTERNATIVE OXIDIZING AGENTS FOR COBALT CMP	15/649,378		7/13/2017
CMC Materials, Inc.	SYSTEMS FOR MIXING A LIQUID AND RELATED METHODS	15/684,470	10,486,124	8/23/2017
CMC Materials, Inc.	NITRIDE INHIBITORS FOR HIGH SELECTIVITY OF TiN-SiN CMP APPLICATIONS	15/706,192		9/15/2017
International Test Solutions, LLC	SEMICONDUCTOR WIRE BONDING MACHINE CLEANING DEVICE AND METHOD	15/723,151	10,361,169	10/2/2017
CMC Materials, Inc.	SURFACE TREATED ABRASIVE PARTICLES FOR TUNGSTEN BUFF APPLICATIONS	15/723,886	11,043,151	10/3/2017
CMC Materials, Inc.	CMP COMPOSITIONS SELECTIVE FOR OXIDE AND NITRIDE WITH IMPROVED DISHING AND PATTERN SELECTIVITY	15/784,949	10,640,679	10/16/2017
International Test Solutions, LLC	Working surface cleaning system and method	15/818,386	10,239,099	11/20/2017
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED SURFACE SCRATCHING	15/817,959		11/20/2017
CMC Materials, Inc.	COMPOSITION AND METHOD FOR REMOVING RESIDUE FROM CHEMICAL-MECHANICAL PLANARIZATION SUBSTRATE	15/825,305	10,522,341	11/29/2017

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CMC Materials, Inc.	TUNGSTEN BUFF POLISHING COMPOSITIONS WITH IMPROVED TOPOGRAPHY	15/864,720	10,647,887	1/8/2018
CMC Materials, Inc.	TUNGSTEN BULK POLISHING METHOD WITH IMPROVED TOPOGRAPHY	15/866,008		1/9/2018
CMC Materials, Inc.	COATED COMPRESSIVE SUBPAD FOR CHEMICAL MECHANICAL POLISHING	15/875,773		1/19/2018
CMC Materials, Inc.	CMP COMPOSITIONS CONTAINING POLYMER COMPLEXES AND AGENTS FOR STI APPLICATIONS	15/920,813	10,584,266	3/14/2018
CMC Materials, Inc.	SELF-STOPPING POLISHING COMPOSITION AND METHOD FOR BULK OXIDE PLANARIZATION	15/934,219	10,619,075	3/23/2018
CMC Materials, Inc.	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS	15/951,358	10,640,680	4/12/2018
CMC Materials, Inc.	CHEMICAL-MECHANICAL PROCESSING SLURRY AND METHODS FOR PROCESSING A NICKEL SUBSTRATE SURFACE	15/951,598	10,968,377	4/12/2018
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING MEMORY HARD DISKS EXHIBITING REDUCED EDGE ROLL OFF	16/000,062	10,479,911	6/5/2018
CMC Materials, Inc.	METHODS AND COMPOSITIONS FOR PROCESSING DIELECTRIC SUBSTRATE	16/018,281	10,639,766	6/26/2018
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN CMP	16/131,180		9/14/2018
International Test Solutions, LLC	WAFER MANUFACTURING CLEANING APPARATUS, PROCESS AND METHOD OF USE	16/136,965	10,741,420	9/20/2018
CMC Materials, Inc.	COMPOSITION AND METHOD FOR METAL CMP	16/208,742	10,968,366	12/4/2018
CMC Materials, Inc.	COMPOSITION AND METHOD FOR COPPER BARRIER CMP	16/208,797	10,988,635	12/4/2018
CMC Materials, Inc.	COMPOSITION AND METHOD FOR COBALT CMP	16/208,703		12/4/2018
CMC Materials, Inc.	COMPOSITION AND METHOD FOR SILICON NITRIDE CMP	16/208,779		12/4/2018
CMC Materials, Inc.	COMPOSITION FOR TUNGSTEN CMP	16/236,962	10,676,647	12/31/2018
CMC Materials, Inc.	SELF-STOPPING POLISHING COMPOSITION AND METHOD FOR BULK OXIDE PLANARIZATION	16/271,508	10,619,076	2/8/2019
International Test Solutions, LLC	NOVEL MATERIAL AND HARDWARE TO AUTOMATICALLY CLEAN FLEXIBLE EXETRONIC WEB	16/283,592	10,843,885	2/22/2019

Registered Owner	Title	Application Number	Patent Number	Filing Date
	ROLLS			
International Test Solutions, LLC	NOVEL MATERIAL AND HARDWARE TO AUTOMATICALLY CLEAN FLEXIBLE EXETRONIC WEB ROLLS	16/283,603	11,155,428	2/22/2019
International Test Solutions, LLC	NOVEL MATERIAL AND HARDWARE TO AUTOMATICALLY CLEAN FLEXIBLE EXETRONIC WEB ROLLS	16/283,607	10,717,618	2/22/2019
International Test Solutions, LLC	NOVEL MATERIAL AND HARDWARE TO AUTOMATICALLY CLEAN FLEXIBLE EXETRONIC WEB ROLLS	16/283,613		2/22/2019
International Test Solutions, LLC	Working surface cleaning system and method	16/290,789	10,406,568	3/1/2019
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING SILICON CARBIDE	16/389,097		4/19/2019
International Test Solutions, LLC	Working surface cleaning system and method	16/438,162		6/11/2019
International Test Solutions, LLC	PICK AND PLACE MACHINE CLEANING SYSTEM AND METHOD	16/460,935	10,792,713	7/2/2019
International Test Solutions, LLC	PICK AND PLACE MACHINE CLEANING SYSTEM AND METHOD	16/460,877		7/2/2019
International Test Solutions, LLC	PICK AND PLACE MACHINE CLEANING SYSTEM AND METHOD	16/460,918		7/2/2019
International Test Solutions, LLC	PICK AND PLACE MACHINE CLEANING SYSTEM AND METHOD	16/460,929		7/2/2019
CMC Materials KK	CHEMICAL-MECHANICAL POLISHING COMPOSITION, RINSE COMPOSITION, CHEMICAL-MECHANICAL POLISHING METHOD, AND RINSING METHOD	17/260,106		7/12/2019
CMC Materials, Inc.	METHOD TO INCREASE BARRIER FILM REMOVAL RATE IN BULK TUNGSTEN SLURRY	16/513,404		7/16/2019
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD UTILIZING ABRASIVE PARTICLES TREATED WITH AN AMINOSILANE	16/664,235	11,034,862	10/25/2019
International Test Solutions, LLC	SYSTEM AND METHOD FOR CLEANING CONTACT ELEMENTS AND SUPPORT HARDWARE USING FUNCTIONALIZED SURFACE MICROFEATURES	16/684,453	11,211,242	11/14/2019
CMC Materials, Inc.	OXIDIZER FREE SLURRY FOR RUTHENIUM CMP	16/706,991		12/9/2019

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	DUAL ADDITIVE COMPOSITION FOR POLISHING MEMORY HARD DISKS EXHIBITING EDGE ROLL OFF	16/729,905		12/30/2019
International Test Solutions, LLC	PICK AND PLACE MACHINE CLEANING SYSTEM AND METHOD	16/794,068		2/18/2020
CMC Materials, Inc.	SELF-STOPPING POLISHING COMPOSITION AND METHOD FOR BULK OXIDE PLANARIZATION	16/797,438	10,920,107	2/21/2020
CMC Materials, Inc.	ADDITIVES TO IMPROVE PARTICLE DISPERSION FOR CMP SLURRY	16/826,409		3/23/2020
CMC Materials, Inc.	SURFACE COATED ABRASIVE PARTICLES FOR TUNGSTEN BUFF APPLICATIONS	16/849,021		4/15/2020
International Test Solutions, LLC	SYSTEM AND METHOD FOR CLEANING WIRE BONDING MACHINES USING FUNCTIONALIZED SURFACE MICROFEATURES	16/855,841	11,318,550	4/22/2020
CMC Materials, Inc.	CHEMICAL-MECHANICAL POLISHING PAD WITH TEXTURED PLATEN ADHESIVE	17/607,743		4/30/2020
CMC Materials, Inc.	CHEMICAL MECHANICAL PLANARIZATION PADS WITH CONSTANT GROOVE VOLUME	16/868,755		5/7/2020
CMC Materials, Inc.	CHEMICAL MECHANICAL PLANARIZATION PADS VIA VAT-BASED PRODUCTION	16/868,965		5/7/2020
International Test Solutions, LLC	DEVICE AND METHOD FOR THERMAL STABILIZATION OF PROBE ELEMENTS USING A HEAT CONDUCTING WAFER	16/872,292	11,035,898	5/11/2020
International Test Solutions, LLC	WAFER MANUFACTURING CLEANING APPARATUS, PROCESS AND METHOD OF USE	16/895,106	10,896,828	6/8/2020
CMC Materials, Inc.	SOLID POLYMER ELECTROLYTE COMPOSITIONS AND METHODS OF PREPARING SAME	16/895,714		6/8/2020
CMC Materials, Inc.	SECONDARY BATTERY CELL WITH SOLID POLYMER ELECTROLYTE	16/895,769		6/8/2020
CMC Materials KK	CHEMICAL-MECHANICAL POLISHING COMPOSITION, RINSE COMPOSITION, CHEMICAL-MECHANICAL POLISHING METHOD, AND RINSING METHOD	17/620,181		6/11/2020
CMC Materials, Inc.	POLISHING PAD EMPLOYING POLYAMINE AND CYCLOHEXANEDIMETHANOL CURATIVES	16/923,688		7/8/2020

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLYSILICON CMP	17/009,961		9/2/2020
QED Technologies International, Inc.	HIGH REMOVAL RATE MAGNETORHEOLOGICAL FINISHING HEAD	17/640,234		9/2/2020
CMC Materials, Inc.	POLISHING COMPOSITION AND METHOD WITH HIGH SELECTIVITY FOR SILICON NITRIDE AND POLYSILICON OVER SILICON OXIDE	17/076,989		10/22/2020
CMC Materials, Inc.	COMPOSITION AND METHOD FOR DIELECTRIC CMP	17/077,070		10/22/2020
CMC Materials, Inc.	COMPOSITION AND METHOD FOR DIELECTRIC CMP	17/077,155		10/22/2020
CMC Materials, Inc.	COMPOSITION AND METHOD FOR SILICON OXIDE AND CARBON DOPED SILICON OXIDE CMP	17/077,295		10/22/2020
CMC Materials, Inc.	SELF-STOPPING POLISHING COMPOSITION AND METHOD	17/077,414		10/22/2020
CMC Materials, Inc.	COMPOSITION AND METHOD FOR SELECTIVE OXIDE CMP	17/077,485		10/22/2020
CMC Materials, Inc.	DERIVATIZED POLYAMINO ACIDS	17/123,295		12/16/2020
CMC Materials, Inc.	CMP COMPOSITION INCLUDING A NOVEL ABRASIVE	17/217,097		3/30/2021
CMC Materials, Inc.	SILICON WAFER POLISHING COMPOSITION AND METHOD	17/379,279		7/19/2021
CMC Materials, Inc.	CMP COMPOSITION INCLUDING ANIONIC AND CATIONIC INHIBITORS	17/384,940		7/26/2021
CMC Materials, Inc.	TITANIUM DIOXIDE CONTAINING RUTHENIUM CHEMICAL MECHANICAL POLISHING SLURRY	17/391,674		8/2/2021
CMC Materials, Inc.	CMP COMPOSITION INCLUDING AN ANIONIC ABRASIVE	63/237,095		8/25/2021
CMC Materials, Inc.	TEXTURED CMP PAD COMPRISING POLYMER PARTICLES	63/240,103		9/2/2021
CMC Materials, Inc.	SILICA-BASED SLURRY FOR SELECTIVE POLISHING OF CARBON-BASED FILMS	17/474,543		9/14/2021
CMC Materials, Inc.	CHEMICAL MECHANICAL PLANARIZATION PAD WITH A RELEASE LINER COMPRISING A PULL TAB	17/478,690		9/17/2021
QED Technologies International, Inc.	DEFLECTOMETRY DEVICE FOR DIFFERENTIAL METROLOGY OF MATERIAL REMOVAL	63/245,887		9/19/2021

Registered Owner	Title	Application Number	Patent Number	Filing Date
CMC Materials, Inc.	SILICA-BASED SLURRY COMPOSITIONS CONTAINING HIGH MOLECULAR WEIGHT POLYMERS FOR USE IN CMP OF DIELECTRICS	63/247,429		9/23/2021
CMC Materials, Inc.	UV-CURABLE RESINS USED FOR CHEMICAL MECHANICAL POLISHING PADS	17/503,422		10/18/2021
CMC Materials, Inc.	AMINE-BASED COMPOSITIONS FOR USE IN CMP WITH HIGH POLYSILICON RATE	63/276,957		11/8/2021
International Test Solutions, LLC	SYSTEM AND METHOD FOR CLEANING CONTACT ELEMENTS AND SUPPORT HARDWARE USING FUNCTIONALIZED SURFACE MICROFEATURES	17/540,943		12/2/2021
CMC Materials, Inc.	SELF-STOPPING POLISHING COMPOSITION AND METHOD FOR HIGH TOPOLOGICAL SELECTIVITY	17/557,412		12/21/2021
CMC Materials, Inc.	SUBPAD DESIGN HAVING POROGENS WITH POLYMERIC SHELLS	17/557,461		12/21/2021
CMC Materials, Inc.	ENDPOINT WINDOW WITH CONTROLLED TEXTURE SURFACE	17/582,667		1/24/2022
CMC Materials, Inc.	COMPOSITION AND METHOD FOR POLISHING BORON DOPED POLYSILICON	17/584,532		1/26/2022
CMC Materials, Inc.	CERIA-BASED SLURRY COMPOSITIONS FOR SELECTIVE AND NONSELECTIVE CMP OF SILICON OXIDE, SILICON NITRIDE, AND POLYSILICON	17/592,279		2/3/2022
CMC Materials, Inc.	CERIA-BASED SLURRY COMPOSITIONS FOR SELECTIVE AND NONSELECTIVE CMP OF SILICON OXIDE, SILICON NITRIDE, AND POLYSILICON	17/592,294		2/3/2022
CMC Materials, Inc.	SILICON CARBONITRIDE POLISHING COMPOSITION AND METHOD	17/592,612		2/4/2022
CMC Materials, Inc.	DUAL ADDITIVE POLISHING COMPOSITION FOR GLASS SUBSTRATES	63/323,192		3/24/2022

SCHEDULE II

Trademarks and Trademark Applications

Registered Owner	Trademark	Application Number	Registration Number	Filing Date
CMC Materials, Inc.	ACTIV-8	87/189,392	5,520,231	9/30/2016
CMC Materials, Inc.	AUSCILLATER	87/189,352	5,788,180	9/30/2016
International Test Solutions, LLC	CCW	77/733,035	3,725,048	5/8/2009
CMC Materials, Inc.	CHAMELEON SEAL	87/189,434	5,514,443	9/30/2016
CMC Materials, Inc.	CLEANROOM	74/418,487	1,851,237	7/19/1993
CMC Materials, Inc.	CMC Logo	88/806,340		2/21/2020
CMC Materials, Inc.	CMC MATERIALS	88/698,404	6,667,318	11/19/2019
CMC Materials, Inc.	CMC MATERIALS & Design	88/719,666	6,667,339	12/9/2019
CMC Materials, Inc.	EPIC	75/541,268	2,363,181	8/24/1998
CMC Materials, Inc.	EPIC POWER	90/581,923		3/16/2021
CMC Materials, Inc.	EPIC POWER & Design	90/581,990		3/16/2021
CMC Materials, Inc.	EQUA-LUBE EIGHTY	87/219,669	5,944,473	10/28/2016
International Test Solutions, LLC	ETCH CLEAN	86/077,492	4,479,239	9/27/2013
CMC Materials, Inc.	FLOW WOLF	87/189,402	5,514,442	9/30/2016
CMC Materials, Inc.	GIGABIT	74/144,981	1,705,722	3/6/1991
CMC Materials, Inc.	GRIZZLY SEAL	87/189,421	5,807,265	9/30/2016
CMC Materials, Inc.	HIPR	78/294,247	2,994,247	8/29/2003
CMC Materials, Inc.	ICUE	78/058,334	2,517,587	4/13/2001
CMC Materials, Inc.	IDIEL	86/199,007	4,613,239	2/20/2014
International Test Solutions, LLC	INTERNATIONAL TEST SOLUTIONS & Design	76/289,860	2,651,534	7/23/2001
CMC Materials, Inc.	LUSTRA	75/793,537	2,632,288	9/7/1999
CMC Materials, Inc.	MEDEA	87/447,687	5,354,755	5/12/2017
QED Technologies International, Inc.	MRF	76/458,117	2,827,173	10/15/2002
CMC Materials, Inc.	NANO-STRIP	78/692,339	3,306,579	8/15/2005
CMC Materials, Inc.	NANO-STRIP	78/929,348	3,949,164	7/13/2006
CMC Materials, Inc.	NEXPLANAR	77/509,846	3,702,810	6/27/2008
International Test Solutions, LLC	PROBE CLEAN	76/289,916	2,599,807	7/23/2001
International Test Solutions, LLC	PROBE FORM	76/289,852	2,642,325	7/23/2001
International Test Solutions, LLC	PROBE LAP	78/948,800	3,251,735	8/9/2006
International Test Solutions, LLC	PROBE POLISH	76/289,858	2,610,970	7/23/2001

Registered Owner	Trademark	Application Number	Registration Number	Filing Date
International Test Solutions, LLC	PROBE POLISH	77/636,417	3,660,513	12/18/2008
International Test Solutions, LLC	PROBE REFRESH	87/606,969	5,947,138	9/13/2017
International Test Solutions, LLC	PROBE SCCRUB	77/636,420	3,660,514	12/18/2008
International Test Solutions, LLC	PROBE SCRUB	76/289,917	2,599,808	7/23/2001
International Test Solutions, LLC	PROBE VERTICAL	87/606,989	5,947,139	9/13/2017
QED Technologies International, Inc.	QED OPTICS	85/527,165	4,303,897	1/27/2012
QED Technologies International, Inc.	QED TECHNOLOGIES	76/458,114	2,777,617	10/15/2002
QED Technologies International, Inc.	Q-FLEX	85/466,012	4,270,737	11/7/2011
International Test Solutions, LLC	SCD	77/733,038	3,725,049	5/8/2009
CMC Materials, Inc.	SEALVALVE	87/189,937	5,969,362	9/30/2016
CMC Materials, Inc.	SEALVALVE	87/978,962	6,010,732	9/30/2016
CMC Materials, Inc.	SEALWELD	75/213,870	2,142,260	12/16/1996
CMC Materials, Inc.	SEALWELD	87/189,442	6,085,978	9/30/2016
CMC Materials, Inc.	SEMI-SPERSE	74/069,266	1,704,025	6/15/1990
CMC Materials, Inc.	SEMI-SPERSE	74/525,909	1,917,115	5/17/1994
CMC Materials, Inc.	SILECT	78/507,283	3,103,184	10/28/2004
International Test Solutions, LLC	STAGE CLEAN	86/037,041	4,517,513	8/13/2013
CMC Materials, Inc.	SUPERGUN	87/189,379	5,938,368	9/30/2016
International Test Solutions, LLC	TCC	77/733,039	3,820,328	5/8/2009
CMC Materials, Inc.	TERABIT	74/436,622	1,870,262	9/17/1993
CMC Materials, Inc.	TOTAL-LUBE #911	87/219,660	5,638,495	10/28/2016
CMC Materials, Inc.	TRANSELE	77/008,348	3,623,364	9/27/2006
CMC Materials, Inc.	TURBOFLO	76/497,871	2,971,771	3/17/2003
CMC Materials, Inc.	ULTRA-ETCH	74/430,501	1,907,795	8/30/1993
CMC Materials, Inc.	UNI-SEAL	87/189,370	5,633,402	9/30/2016
CMC Materials, Inc.	VALVE CLEANER PLUS	87/219,680	5,498,636	10/28/2016
CMC Materials, Inc.	VALVEPRO	87/189,409	5,938,369	9/30/2016
CMC Materials, Inc.	VIPER	77/916,210	4,053,560	1/20/2010
CMC Materials, Inc.	WIN	77/241,017	3,456,932	7/27/2007
CMC Materials, Inc.	X-PAND	75/328,764	2,243,649	7/22/1997